



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-04-22
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U031R8I6	205X*459CSXA	A	9991	2024-04-22
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	25	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Tin - 3.5Ag	Not Applicable	NAC	0	
Package designator	Package size	Number of instances	Shape	
BGA	5x5	64	Bulk solder	
Comment	Package : A019 UFBGA 5X5X0.6 64L P 0.5 MM 8526322			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-23rd January 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	205X*459CSXA		25.0000		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	1.492	mg	supplier	die	Silicon (Si)	7440-21-3		1.287	mg	862601	51480
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	6702	400
				supplier	metallization	Copper (Cu)	7440-50-8		0.087	mg	58311	3480
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.028	mg	18767	1120
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	670	40
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	670	40
				supplier	Passivation	Silicon Nitride	12033-89-5		0.022	mg	14745	880
				supplier	Passivation	Silicon Oxide	7631-86-9		0.056	mg	37534	2240
				Substrate (A322870)	Other Organic Materials	9.990	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary	
supplier	BT-substrate	Glass cloth	65997-17-3						2.754	mg	275650	110150
supplier	BT-substrate	Copper foil	7440-50-8						3.492	mg	349500	139660
supplier	Solder mask	Ethanol, 2-(2-ethoxyethoxy)-, 1-acetate	112-15-2						1.154	mg	115500	46154
supplier	Solder mask	Naphtha (petroleum), heavy aromatic	64742-94-5						1.349	mg	135000	53946
SVHC	Solder mask	Methanone, (diphenylphosphoryl)(2,4,6-trimethyl)	75980-60-8						0.008	mg	800	320
supplier	Solder mask	TALC (CONTAINING NO ASBESTOS FIBRES)	14807-96-6						0.365	mg	36500	14585
supplier	Solder mask	Dipropylene glycol Methylene Ether Acetate	88917-22-0						0.265	mg	26500	10589
SVHC	Solder mask	1,3,5-Triazine-2,4,6-triamine	108-78-1						0.005	mg	550	220
DAF (ATB-125(30))	Other Organic Materials	2.154	mg	supplier	film	Butadiene, acrylonitrile polymer, carboxy-terminated	68610-41-3		1.503	mg	697850	60127
				supplier	film	Formaldehyde, polymer with (chloromethyl)oxiran	37382-79-9		0.479	mg	222350	19158
				supplier	film	dapsone	80-08-0		0.101	mg	46900	4041
				supplier	film	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.036	mg	16900	1456
				supplier	film	reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6		0.034	mg	16000	1379
Bonding wire (Cu)	Precious metals	0.329	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.001	mg	3500	46
				supplier	Bonding wire	Copper (Cu)	7440-50-8		0.318	mg	965500	12706
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.010	mg	31000	408
Encapsulation (KE-G1250AAS)	Other inorganic materials	9.479	mg	supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		8.531	mg	900000	341244
				supplier	Molding Compound	Epoxy resin	Proprietary		0.379	mg	40000	15166
				supplier	Molding Compound	Phenol resin	Proprietary		0.531	mg	56000	21233
				supplier	Molding Compound	Carbon Black	1333-86-4		0.038	mg	4000	1517
Solder balls (96.5Sn/3.5Ag)	Other Nonferrous metals & alloys	1.556	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		1.504	mg	966350	60146
				supplier	Matte Sn	Silver(Ag)	7440-22-4		0.052	mg	33650	2094